

## 12英寸自动减薄设备

12 INCH AUTOMATIC GRINDER

# AG7500

- **最大有效加工尺寸 (mm)**  
Maximum effective product size (mm)  
**Max.  $\phi 300$  ( $\phi 4'' \sim \phi 12''$ )**

- **主轴配置方式**  
Configuration method of spindle  
**单主轴**  
Single-spindle



### ● 特点 FEATURE

采用直观便捷的整机操作界面，可选择不同尺寸不同规格的加工配置文件。

With the intuitive and convenient operation interface of the whole machine, you can select processing configuration files of different sizes and specifications.

采用精密进口滚珠丝杆、直线导轨，高精度电机，进行 Z 向精密控制；最小分辨率在 0.1UM/S。

Precision imported ball screw, linear guide rail and high-precision motor are used for Z-direction precision control; The minimum resolution is 0.1um/s.

可有效于硬质和脆性材料以及电子元件产品的研削加工。

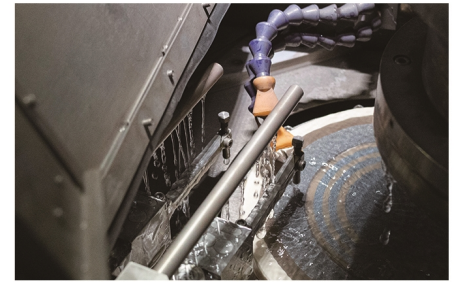
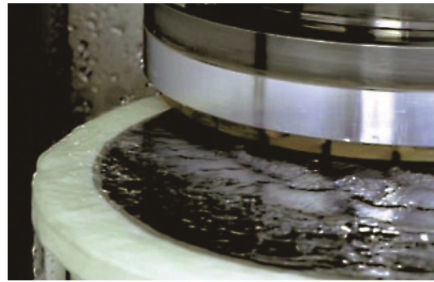
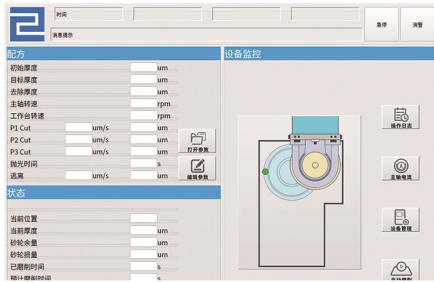
In-Feed spindle feed type High precision grinding.

采用高刚性气浮主轴，高可靠性与运动精度的承片组件，加之高精度测厚仪；保证加工全程的稳定、可靠。

Adopt high rigid air bearing spindle, high reliability and motion precision bearing plate assembly, and high precision thickness gauge; Ensure the stability and reliability of the whole process.

单主轴，单工作台，结构紧凑的减薄机，最大可对应 12 英寸的加工物。

Single-spindle, single-worktable, compact thinning machine, which can correspond to a maximum of 12 inches of workpiece.



## 功能 FUNCTION

注: 「\*」为选配功能, 支持个性化定制  
PS: 「\*」 is an optional feature that can be customized by the customer

### 操作日志记录

Operation log record

### 功能模块化&软件定制

Functional modularity & software customization

### 实时高精度接触式晶圆测厚

Real-time, high-precision contact wafer thickness measurement

### 抽雾过滤系统

Mist extraction and filtration system

### 12英寸晶圆等材料磨削

Grinding of 12-inch wafer and other materials

### 真空预警与真空管路去水

Vacuum warning and vacuum line de-watering

### 主轴水冷系统

Spindle water cooling system

## 参数 PARAMETER

主轴	Spindle	高频电机内嵌空气静压主轴	High-frequency motor built-in aerostatic spindle
额定输出功率 (kW)	Rated output power (kW)	7.5	
转速 (Rpm)	Rotary speed (Rpm)	0-4000	
Z轴 Z axis	行程 (mm)	80	
	进刀速度 (μm)	Feed speed (μm)	0.0001-0.08
	快退速度 (μm)	Fast rewind speed (μm)	50
	最小位移量 (μm)	Minimum displacement (μm)	0.1
高度计 Altimeter	分辨率 (μm)	Resolution (μm)	0.1
	测量范围 (μm)	Measuring range (μm)	0-1250
	分辨率 (μm)	Resolution (μm)	0.1
吸盘 Sucker	重复精度 (μm)	Repetition precision (μm)	±0.5
	工作台型式	Workbench type	多孔陶瓷式工作台 Porous ceramic worktable
磨轮 Mill wheel	转速 (Rpm)	Rotary speed (Rpm)	0-500
	工作台清洗	Workbench cleaning	油石手动清洗 Manual cleaning of oilstone
真空发生器 Vacuum generator	金刚石砂轮 (mm)	Diamond grinding wheel (mm)	Ø300
	排风速度	Exhaust speed	≥5m <sup>3</sup> /min
	真空压力 (kPa)	Vacuum pressure (kPa)	-90(水温 15°C,流量 1L/min 时) -90 (at water temperature of 15 °C and flow of 1L/min)
加工精度 Machining accuracy	电动机功率 (kW)	Motor power (kW)	2.4
	用水量 (L/min)	Water consumption (L/min)	3(水温>22°C),1(水温<22°C) 3 (water temperature>22 °C), 1 (water temperature<22 °C)
	单片晶圆内厚度差 (μm)	Thickness difference in single wafer (μm)	±3
设备重量 (kg)	不同间晶圆厚度差 (μm)	Thickness difference between different wafers (μm)	±3
	精加工面粗糙度	Finish surface roughness	R <sub>y</sub> 0.13(2000#) R <sub>y</sub> 0.15(1400#)
设备尺寸/W*D*H (mm)	Weight (kg)	≈2,100	
	Size / W*D*H (mm)	840*1,920*1,750	

## 应用 APPLICATION

